

Amendments to the Abstract

01 A method of machining a glass substrate by using a laser, in which a low-permittivity, low-dielectric-loss glass substrate capable of coping with mass production processes is made applicable as the substrate of a high-frequency circuit intended for microwave and millimeter-wave bands in particular. For that purpose, a glass substrate is provided in which the amount of air bubbles in glass is ~~arbitrary~~ arbitrarily controlled to improve the workability of the substrate itself. Then, the glass substrate is machined while being irradiated with a pulsed laser for a plurality of times, thereby improving the machining shape ~~[[tol]]~~ of the glass substrate. Since glass substrates which are typically difficult to machine can be easily applied to the fabrication of high-frequency circuits, it becomes possible to supply high-performance circuits and apparatuses widely to the public.